



SPN160T15

N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN160T15 is the N-Channel enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. The SPN160T15 has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON) and fast switching speed.

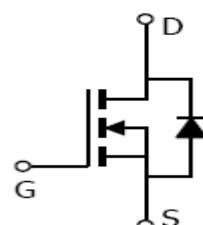
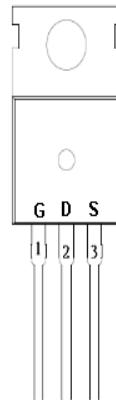
APPLICATIONS

- DC/DC Converter
- Load Switch
- SMPS Secondary Side Synchronous Rectifier
- Motor Control
- Power Tool

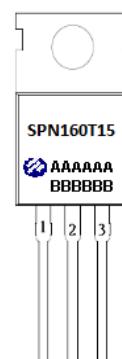
FEATURES

- ◆ 150V/160A,R_{DS(ON)}= 6mΩ@V_{GS}=10V
- ◆ Super high density cell design for extremely low R_{DS (ON)}
- ◆ Exceptional on-resistance and maximum DC current capability

PIN CONFIGURATION



PART MARKING



A : Lot Code
B : Date Code



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PIN DESCRIPTION

TO-220-3L

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN160T15T220TGB	TO-220-3L	SPN160T15

※ SPN160T15T220TGB : Tube ; Pb – Free ; Halogen – Free

ABSOLUT MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	150	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Silicon Limited)	T _c =25°C	160	A
	T _c =100°C	113	
Pulsed Drain Current	I _{DM}	545	A
Single Pulse Avalanche Energy (T _c =25°C , L=0.4mH.)	E _{AS}	720	mJ
Power Dissipation (TO-220-3L)	T _c =25°C	P _D	W
Operating Junction Temperature	T _J	-55~150	°C
Storage Temperature Range	T _{STG}	-55~150	°C
Thermal Resistance-Junction to Case (TO-220-3L)	R _{θJC}	0.35	°C/W



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ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	150			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	2.0		4.0	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =150V, V _{GS} =0V T _J =25°C,			1	uA
		V _{DS} =150V, V _{GS} =0V, T _J =100°C			100	
Drain-Source On-Resistance	R _{DSS(on)}	V _{GS} =10V, I _D =20A		5.4	6	mΩ
Forward Transconductance	g _f	V _{DS} =5V, I _D =20A		80		S
Gate resistance	R _g	V _{DS} =0V, V _{GS} =0V f=1MHz		2.7		Ω
Diode Forward Voltage	V _{SD}	I _F =20A, V _{GS} =0V		0.9	1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =75V, V _{GS} =10V I _D =20A		80		nC
Gate-Source Charge	Q _{gs}			28		
Gate-Drain Charge	Q _{gd}			12		
Input Capacitance	C _{iss}	V _{DS} =75V, V _{GS} =0V f=1MHz		6320		pF
Output Capacitance	C _{oss}			462		
Reverse Transfer Capacitance	C _{rss}			7.5		
Turn-On Time	t _{d(on)}	V _{DD} =75V, I _D =20A, V _{GS} =10V R _G =10Ω		27		nS
	t _r			21		
Turn-Off Time	t _{d(off)}			38		
	t _f			14		
Reverse Recovery Time	t _{rr}	VR=75V, I _F =20A, dI _F /dt=100A/uS		86		nS
Reverse Recovery Charge	Q _{rr}			160		nC



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TYPICAL CHARACTERISTICS

Fig 1. Typical Output Characteristics

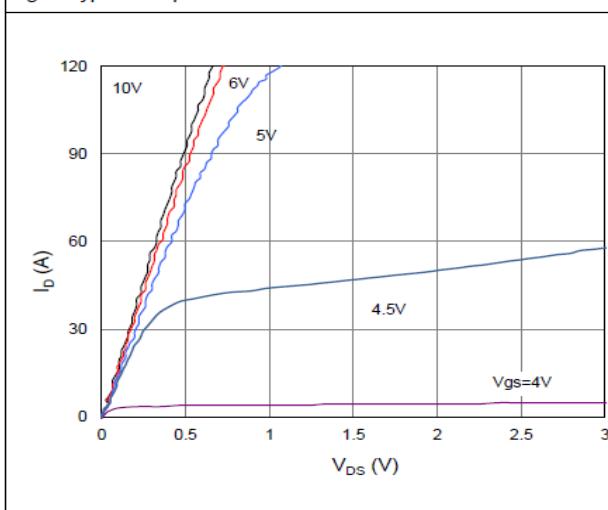


Figure 2. On-Resistance vs. Gate-Source Voltage

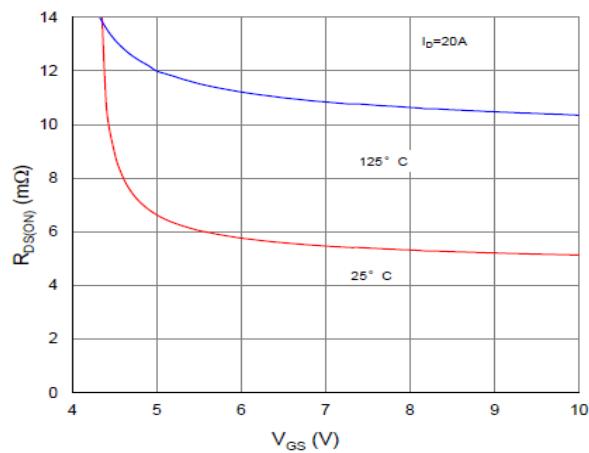


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

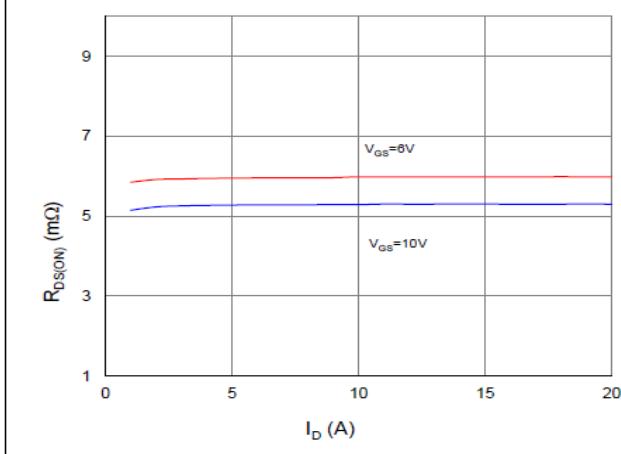


Figure 4. Normalized On-Resistance vs. Junction Temperature

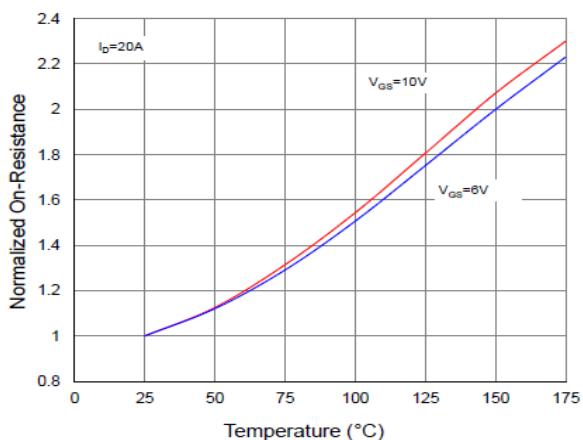


Figure 5. Typical Transfer Characteristics

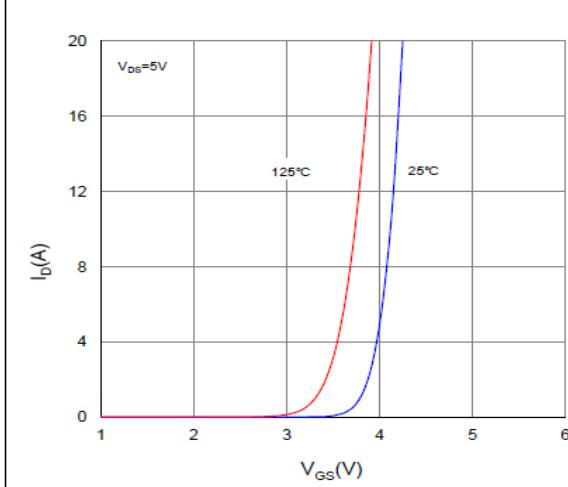
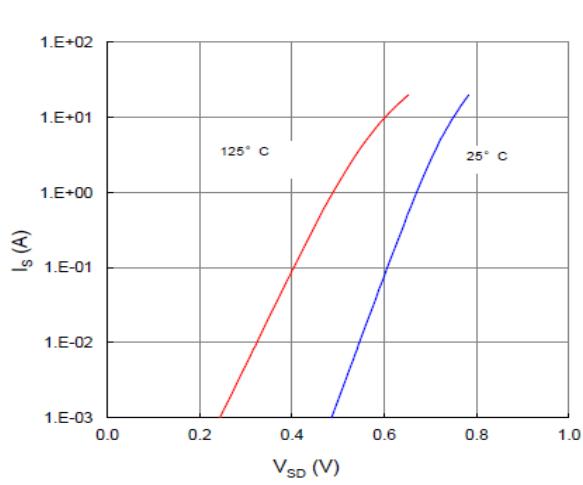


Figure 6. Typical Source-Drain Diode Forward Voltage





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TYPICAL CHARACTERISTICS

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

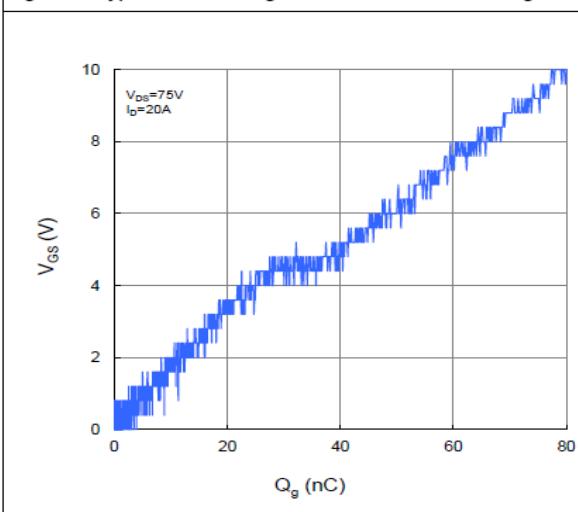


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

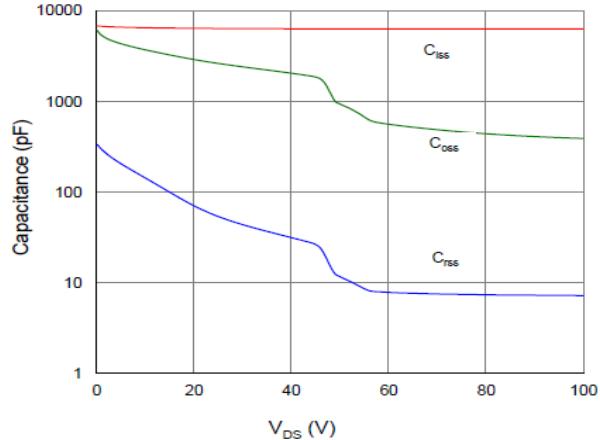


Figure 9. Maximum Safe Operating Area

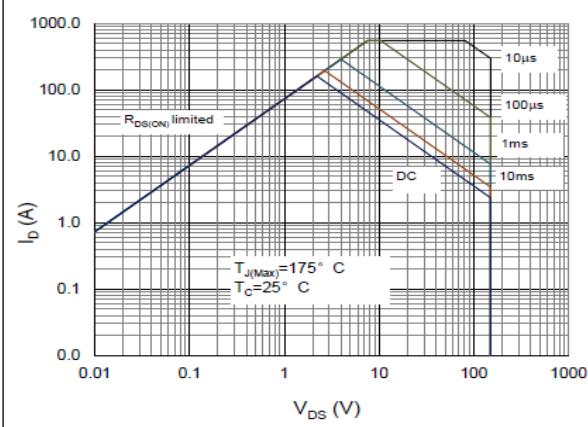


Figure 10. Maximum Drain Current vs. Case Temperature

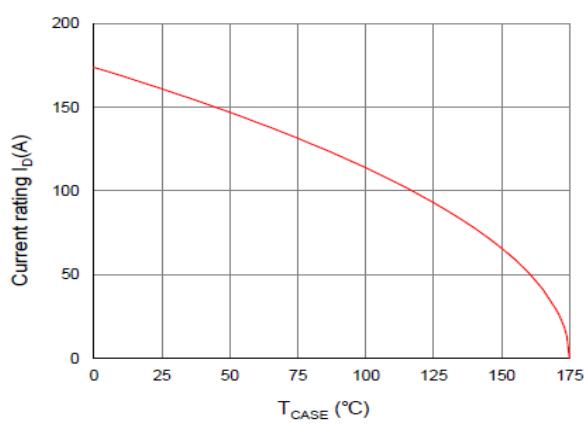
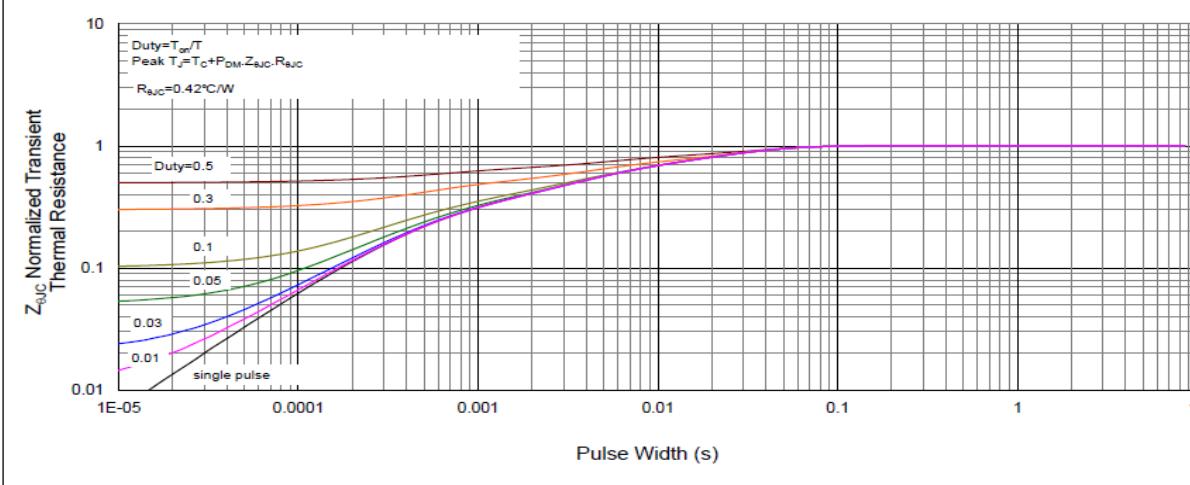


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case





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